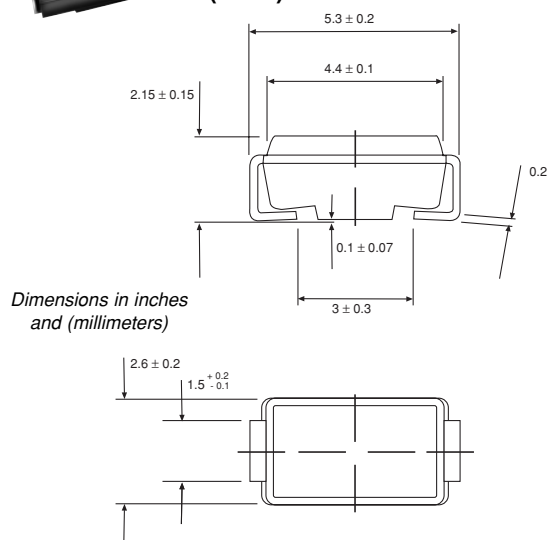
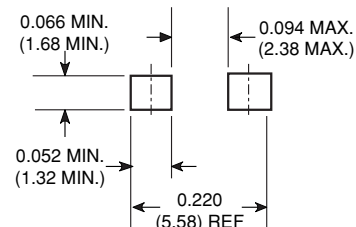


**DO-214AC
(SMA)**

Schottky Barrier Rectifiers

Reverse Voltage 90
Forward Current 1.0A

Mounting Pad Layout



Mechanical Data

Case: JEDEC DO-214AC molded plastic body**Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026**High temperature soldering guaranteed:** 250°C/10 seconds at terminals**Polarity:** Color band denotes cathode end**Weight:** 0.002oz., 0.064g

Features

- Low power loss, high efficiency
- Low profile surface mount package
- Built-in strain relief
- Very low switching losses
- Low reverse current
- High surge capability
- Guardring for overvoltage protection
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0

Maximum Ratings and Thermal Characteristics (T_A = 25°C unless otherwise noted)

| Parameter | Symbol | BYS12-90 | Unit |
|--|-----------------------------------|--|------|
| Device marking code | | BYS 209 | |
| Maximum repetitive peak reverse voltage | V _{RRM} | 90 | V |
| Maximum average forward rectified current | I _{F(AV)} | 1.5 | A |
| Peak forward surge current single half sine-wave superimposed on rated load at 8.3ms at 10ms | I _{FSM} | 40 30 | A |
| Maximum Thermal Resistance – Junction Ambient | R _{θJA} | 150 ⁽¹⁾ 125 ⁽²⁾ 100 ⁽³⁾ | °C/W |
| Voltage rate of change (V _R) | dv/dt | 10,000 | V/μs |
| Junction and storage temperature range | T _J , T _{STG} | –55 to +150 | °C |

Electrical Characteristics (T_A = 25°C unless otherwise noted)

| | | | | |
|---|---|----------------|------------|----------|
| Maximum instantaneous forward voltage at: ⁽⁴⁾ | I _F = 1A I _F = 15mA | V _F | 750 360 | mV |
| Maximum DC reverse current at V _{RRM} ⁽⁴⁾ | T _J = 25°C T _J = 100°C | I _R | 100 1 | μA mA |

Notes: (1) Mounted on epoxy-glass hard tissue
(2) Mounted on epoxy-glass hard tissue, 50 mm² 35 μm Cu
(3) Mounted on Al-oxide-ceramic (Al₂O₃), 50 mm² 35 μm Cu
(4) Pulse test: 300μs pulse width, 1% duty cycle

Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig. 1 – Forward Current vs. Forward Voltage

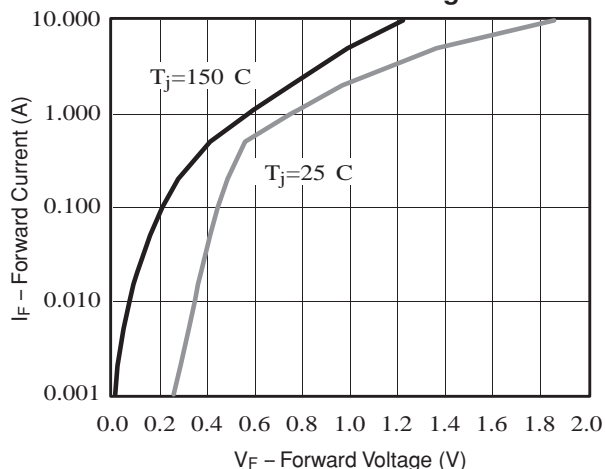


Fig. 4 – Reverse Current vs. Junction Temperature

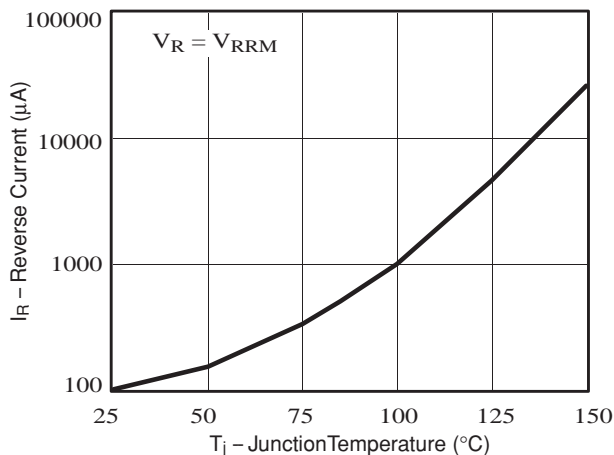


Fig. 2 – Max. Average Forward Current vs. Ambient Temperature

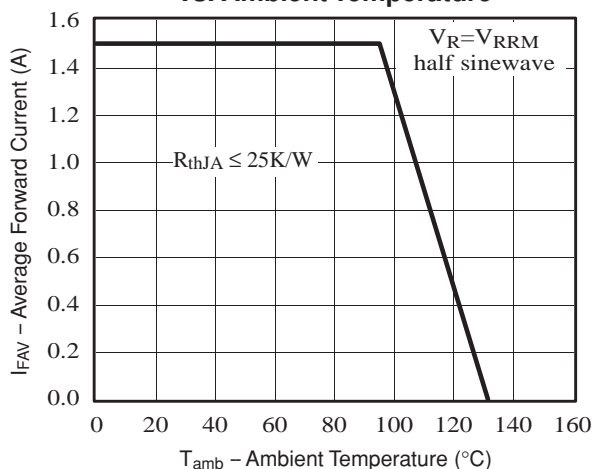


Fig. 5 – Max. Reverse Power Dissipation vs. Junction Temperature

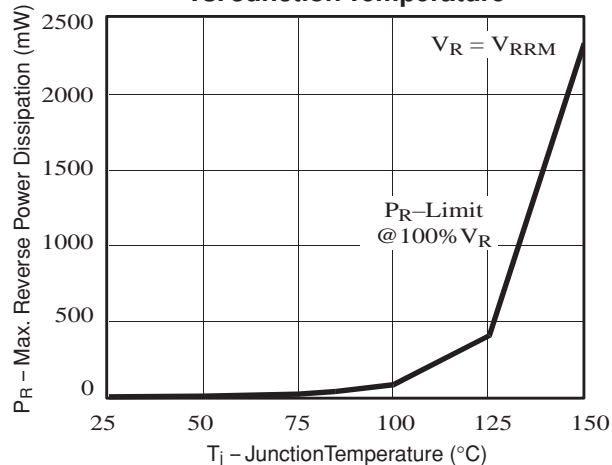


Fig. 3 – Max. Average Forward Current vs. Ambient Temperature

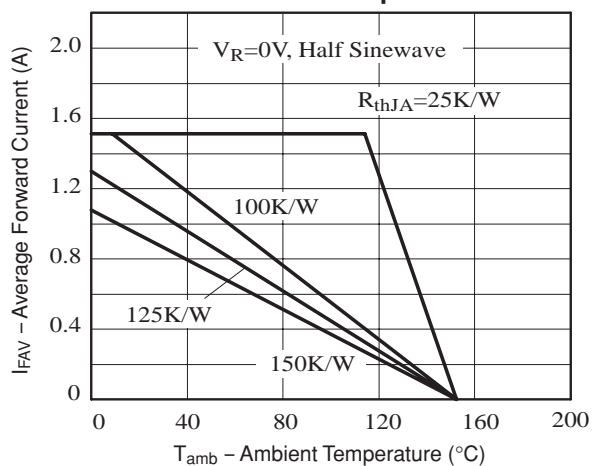
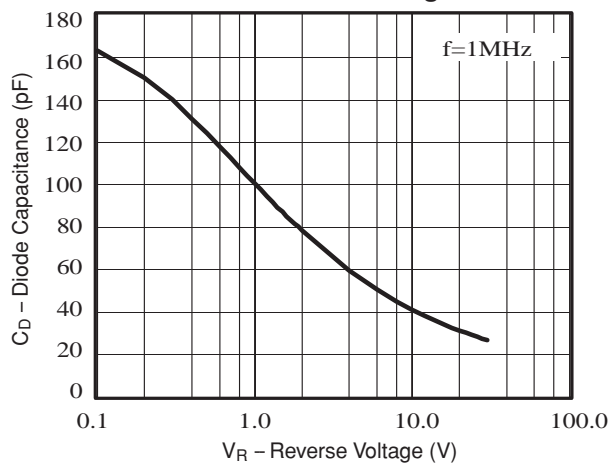


Fig. 6 – Diode Capacitance vs. Reverse Voltage





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